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Soft soldering fluxes - Test methods - Part 5: Copper mirror test (ISO/FDIS 9455-5:2014)

Flussmittel zum Weichlöten - Prüfverfahren - Teil 5: Kupferspiegeltest (ISO/FDIS 9455-5:2014)

Flux de brasage tendre - Méthodes d'essai - Partie 5: Essai au miroir de cuivre (ISO/FDIS 9455-5:2014)

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Copper mirror test

Flux de brasage tendre — Méthodes d'essai —

Partie 5: Essai au miroir de cuivre

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Foreword

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The committee responsible for this document is ISO/TC 44, *Welding and allied processes*, Subcommittee SC 12, *Soldering materials*.

This second edition cancels and replaces the first edition (ISO 9455-5:1992), which has been technically revised.

Requests for official interpretations of any aspect of this International Standard should be directed to the Secretariat of ISO/TC 44/SC 12 via your national standards body. A complete listing of these bodies can be found at www.iso.org.

ISO 9455 consists of the following parts, under the general title *Soft soldering fluxes — Test methods*:

— *Part 1: Determination of non-volatile matter, gravimetric method*

— *Part 2: Determination of non-volatile matter, ebulliometric method*

— *Part 3: Determination of acid value, potentiometric and visual titration methods*

— *Part 5: Copper mirror test*

— *Part 6: Determination and detection of halide (excluding fluoride) content*

— *Part 8: Determination of zinc content*

— *Part 9: Determination of ammonia content*

— *Part 10: Flux efficacy test, solder spread method*

— *Part 11: Solubility of flux residues*

— *Part 13: Determination of flux spattering*

— *Part 14: Assessment of tackiness of flux residues*

— *Part 15: Copper corrosion test*

